



TECHNICAL BULLETIN

Model	Stock No.	Issued on
AMCM-860D	7766D	Nov. 18, 2015
ACM-806A	7765A	Nov. 18, 2015
DHDC-UV	6265A	Nov. 18, 2015
DHDC-DV	6264A	Nov. 18, 2015
MDDM-860	6273	Nov. 18, 2015
MDDA-860	6277	Nov. 18, 2015

HE-12 Series Rack Chassis module mounting configuration recommendations for optimum heat dissipation.

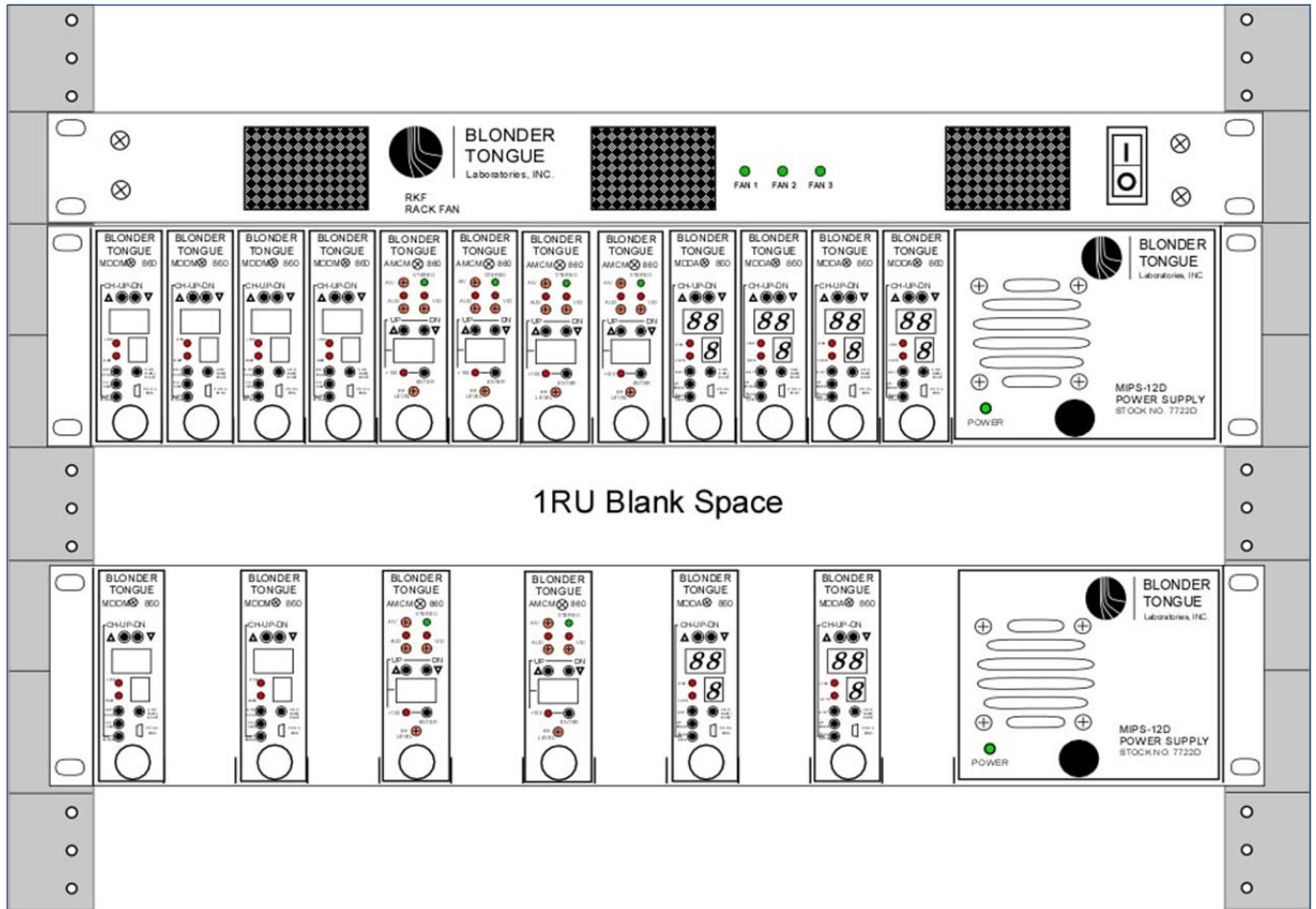
Overview

The 2nd generation of modules listed above for the HE-12 Series rack chassis and power supply dissipates considerably higher wattages as compared to the initial MICM modulators. The installation configuration must provide the means to handle the additional heat generated in order to avoid potential temperature related failures.

When rack fans are not deployed, only 6 of these modules should be installed in the MIRC-12 rack chassis with an empty slot between them. Additionally, a 1RU (minimum) space should be provided above and below the chassis.

The MIRC-12 can be fully loaded with 12 of these modules only when exhaust fans are installed in the rack to remove the heat. The Blonder Tongue RKF stock# 3913 can be installed directly above the HE-Series chassis to exhaust the hot air out the front of the rack. The RKF (or equivalent) is required on top of each fully loaded chassis. A 1RU space for air flow should also be provided at the bottom of each fully loaded chassis. Following the installation configuration drawing below will ensure optimum system operation.





Example configuration

